Thermal Management Products

Product Type	Thermal Management Products								
Family	BGA Heat Sink	Board Level Heat Sink	Extruded Heat Sink	Bonded Fin Heat Sink	Clamp Systems	Cold Plates	Thermal Compounds	Adhesives	Interface Materials	Aluminum Extrusion
Description	*Heat sinks for micro applications*	*For surface mount and thru-hole semi conductors*	*For power semi-conductors*	*Natural convection and forced convection heat sinks*	*For compression devices*	*For high power applications*	*For installation and improved thermal performance*	*Used in bonded fin heat sinks*	*Thermally conductive insulators*	*Standard and custom shapes available*
Series#	624, 625	569, 579, 589	621, 623, 301	510, 511, 512	130	180-12	120	DeltaBond 152	173	Flatback
	659, 655	599, 643, 663	302, 303, 401	392,	139	180-20	122	DeltaBond 153	174	L-style
	658, 660	661, 217, 218	403, 413, 423	Custom Assy	143		126	DeltaBond 154	175	Center Channel
	642, 662	206, 230, 234	431, 433, 435	maxiTHERM Series 1	144			DeltaBond 155		Multi Channel
	628, 630	241, 262, 233	441, 465, 476	maxiTHERM Series 2	143			DeltaBond 156		Flatback w/mounting feet
	698, 798	236, 275, 231	486, 489, 490		146					T-style
	643, 609	235, 243, 239	394, 395, 396		132					H-style
	619, 602	265, 286DB	557, 558, 559		133					Double Sided
	604, 605	273, 274, 281	517, 527, 518							Mounting Shelf
	606, 607	240, 242, 232	528, 537, 547							Press Pack
	610, 611	238, 251, 244								Power Module
	612, 613	245, 246, 247								Forced Convection
	614, 615	248, 249, 288								Modular Extrusions/Enclosures
	616, 617	271, 270, 272								Hollow
	618, 619	280, 280, 290								Misc
	620, 622	250, 237, 252								
		291, 260, 258								
		260, 258, 292								
		634, 637, 626								
		627, 647, 657								
		677, 690, 680								
		601, 603, 641								
Applications	*Shaded box indicates product is applicable with the application.								
Telecomm	🟥	🟥	🟥	🟥		🟥	🟥	🟥	🟥	🟥
Computer	🟥	🟥	🟥				🟥	🟥	🟥	🟥
Consumer	🟥	🟥	🟥				🟥	🟥	🟥	🟥
Industrial			🟥	🟥	🟥	🟥	🟥	🟥	🟥	🟥
Instrumentation	🟥	🟥	🟥	🟥		🟥	🟥	🟥	🟥	🟥
Medical	🟥	🟥	🟥	🟥	🟥	🟥	🟥	🟥	🟥	🟥
Mil/Aero	🟥	🟥	🟥	🟥	🟥	🟥	🟥	🟥	🟥	🟥
Transportation			🟥	🟥	🟥	🟥			🟥	🟥

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Digi-Key Product Selection Guide

Integrated Heat Sinks

Heat sinks for microprocessors, ASICs, SRAM, BGAs, multichip modules, and other integrated circuits.

Board Level Power Semiconductor Heat Sinks

A wide variety of heat dissipators with various attachment mechanisms for surface mount and thru-hole power semiconductors packaged in industry standard plastic, ceramic, and metal cases such as D2Pak, TO-220, TO-3 to TO-247, DO-4 to DO-11, multiwatt, hex-type, and stud mount devices.

Extruded Heat Sinks

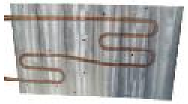
For cooling single and multiple high power devices packaged in industry standard semiconductor case styles:TO-3 to TO-247, DO-4 to DO-30, hex-type, and stud mount; press pack devices; power modules; SCRs, IGBTs; I/0 devices; and other isolated flat base devices in both natural and forced convection.

Bonded Fin Heat Sinks

A variety of Natural Convection, Forced Convection, and Custom Bonded Fin Assemblies.

Precision Compression Clamp Systems

Mounting clamps for compression-type devices to 5,250 in. (133.4 mm) diameter and clamp force requirements ranging from 800 lbs. (262.9 kg) to 16,000 lbs. (7257.5 kg). A wide variety of Press Pack Heat Sinks are offered that are compatible with these mounting clamp series.

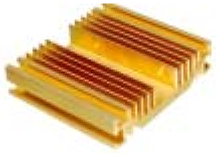


Liquid Cold Plates

For higher power applications where conventional cooling is no longer acceptable.

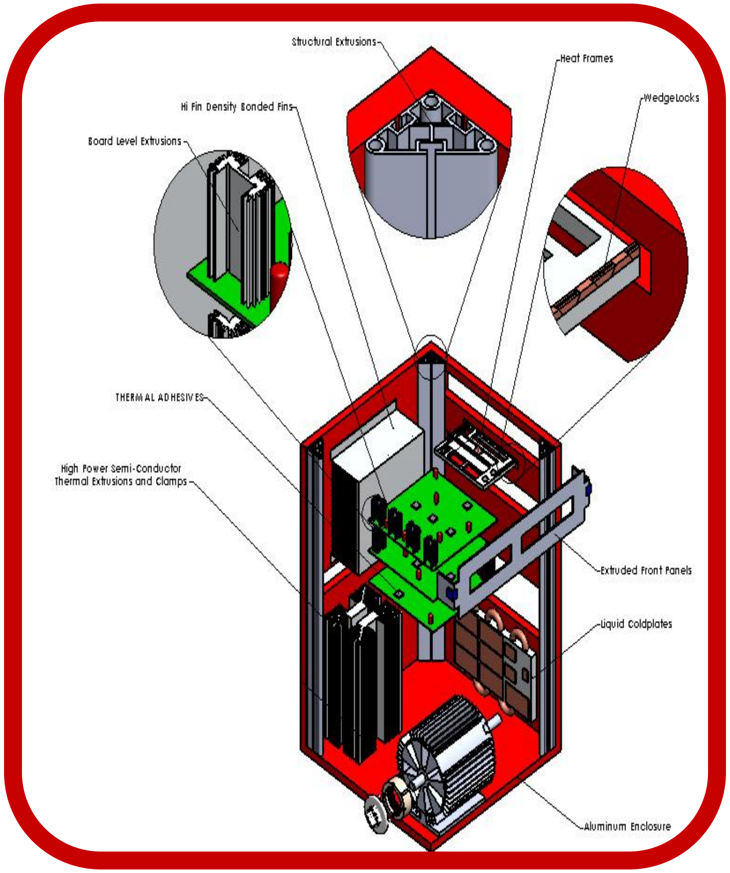
Thermal Accessory Products

Accessory products that facilitate installation and improve the thermal performance of both standard and custom heat dissipation components. Included are thermal joint compounds; filled epoxy systems; adhesives; thermally conductive insulating wafers, washers, pads and mounting hardware.



Aluminum Extrusion Profiles

Flat back , L-style, Center Channel,Multi Channel, Flatback with Integral Mounting Feet, T-style, H-style, Double-Sided , Mounting Shelf, Press Pack, Power Module, Modular



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